February 19, 2021

80th Issuance of Domestic Unsecured Straight Bonds

ACOM CO., LTD. has reached a decision to make its 80th issuance of domestic unsecured straight bonds, as outlined below. The funds procured through this issuance will be used for partial repayment of long-term loans payable.

Name of issuance	ACOM CO., LTD. 80th issuance of domestic unsecured straight bonds
Total value	10 billion yen
Interest rate	0.280% annually
Individual bond value	100 million yen
Issue price	Face value 100 yen
Redemption price	Face value 100 yen
Application period	February 19, 2021
Payment date	February 26, 2021
Maturation date	February 26, 2026
Application of funds procured	Partial repayment of long-term loans payable
Trustee	Mitsubishi UFJ Morgan Stanley Securities Co., Ltd. SMBC Nikko Securities Inc. Daiwa Securities Co. Ltd. Nomura Securities Co., Ltd.
Transfer agent	MUFG Bank, Ltd.
Credit ratings	Japan Credit Rating Agency, Ltd.: A+
	Rating and Investment Information, Inc.: BBB+

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